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SHEET <u>1</u> of <u>3</u>

INFORMATION DISCLOSURE

Atty. Docket No.

Serial No.

**CITATION** 

PTO-1449

NTI-004

09/814,025

**Applicant** 

KARKLIN, Linard

**Filing Date** 

Group

3/20/2001

2623

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
S.A	6,130,750	10/10/2000	Ausschnitt, et al.	356	401	8/28/1997
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S.A	2002/0164064 A1	11/7/2002	Karklin, et al.	382	145	3/20/2001
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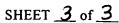
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Atty. Docket No. Serial No. NTI-004 09/814,025 INFORMATION DISCLOSURE **CITATION Applicant** KARKLIN, Linard PTO-1449 Group Filing Date 3/20/2001 2623 OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) EXAMINER'S CITATION INITIALS Lin, B.J., et al., "Single-Level Electric Testsites for Phase-Shifting Masks", SPIE, Vol. 1673, pp. 221-228, March 9-11, 1992.

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PTO-1449

Atty. Docket No. NTI-004

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SA	WO 00/67074 A I	11/9/00	PCT					
S.A	WO 00/67075 A1	11/9/00	PCT					
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